

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold

Germany

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Product image

















Similar to illustration

OMNIMATE Power BV / SV 7.62HP – the 28 kVA performance class

Tailor-made solutions for high performers

More power reserves for higher load bearing capacity: The OMNIMATE Power BV / SV 7.62HP is the middle-class of the power connector systems. It has a large clamping capacity, high overload resistance and the largest range of variants and accessories to choose from: the high performer of the HP range. HP means High Performance – this performance covers a great deal: the full rated current up to 50°C without derating, unlimited 600-V approval according to UL, and the additional finger safety for 400 V-TN systems (+ 3.0 mm) in compliance with the application directive IEC 61800-5-1.

General ordering data

Туре	SV-SMT 7.62HP/02/270SF 2.6SN BK BX
Order No.	<u>2499940000</u>
Version	PCB plug-in connector, male header, Screw flange, THT/THR solder connection, 7.62 mm, Number of poles: 2, 270°, Solder pin length (I): 2.6 mm, tinned, black, Box
GTIN (EAN)	4050118513363
Qty.	60 pc(s).
Product data	IEC: 1000 V / 41 A UL: 300 V / 40.5 A
Packaging	Box

Creation date September 9, 2020 11:13:32 AM CEST



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Technical data

Dimensions and weights

Height of lowest version	11.4 mm	Depth	28.3 mm
Depth (inches)	1.114 inch	Net weight	4.4 g

System specifications

Product family	OMNIMATE Power - series	Type of connection					
	BV/SV 7.62HP	.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	Board connection				
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)					
	connection		7.62 mm				
Pitch in inches (P)	0.3 inch	Outgoing elbow	270°				
Number of poles	2	Number of solder pins per pole	2				
Solder pin length (I)	2.6 mm	Solder pin length tolerance	+0.1 / -0.3 mm				
Tolerance of solder pin position	± 0.1 mm	Solder pin dimensions	0.8 x 1.0 mm				
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (D)+ 0,1 mm					
L1 in mm	7.62 mm	L1 in inches	0.3 inch				
Number of rows	1	Pin series quantity	1				
Touch-safe protection acc. to DIN VDE	uch-safe protection acc. to DIN VDE safe to back of hand above		Touch-safe protection acc. to DIN VDE				
57 106	the printed circuit board	0470	IP 20				
Volume resistance	2.00 mΩ	Tightening torque for screw flange, min. 0.2 Nm					
Tightening torque for screw flange, max	c. 0.3 Nm	Plugging cycles 25					
ugging force/pole, max. 12 N		Pulling force/pole, max.	7 N				

Material data

Insulating material	PA GF HT3	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	I
Comparative Tracking Index (CTI)	≥ 600	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	3	UL 94 flammability rating	V-0
Contact material	Copper alloy	Contact surface	tinned
Layer structure of solder connection	13 µm Ni / 46 µm Sn matt	Layer structure of plug contact	13 μm Ni / 46 μm Sn matt
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	130 °C
Temperature range, installation, min.	-25 ℃	Temperature range, installation, max.	130 °C

Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles					
	IEC 60664-1, IEC 61984	(Tu=20°C)	41 A				
Rated current, max. number of poles		Rated current, min. number of poles					
(Tu=20°C)	41 A	(Tu=40°C)	41 A				
Rated current, max. number of poles		Rated voltage for surge voltage class /					
(Tu=40°C)	41 A	pollution degree II/2	1,000 V				
Rated voltage for surge voltage class /		Rated voltage for surge voltage class /					
pollution degree III/2	630 V	pollution degree III/3	630 V				
Rated impulse voltage for surge voltage		Rated impulse voltage for surge voltage					
class/ pollution degree II/2	6 kV	class/ pollution degree III/2	6 kV				
Rated impulse voltage for surge voltage		Short-time withstand current resistance					
class/ contamination degree III/3	6 kV		3 x 1s with 420 A				
Clearance, min.	6.9 mm	Creepage distance, min.	9.6 mm				



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Rated data acc. to UL 1059

Institute (cURus)	A	Certificate No. (cURus)					
			E60693				
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group C / UL 1059)	300 V				
Rated voltage (Use group D / UL 1059)	300 V	Rated current (Use group B / UL 1059)	40.5 A				
Rated current (Use group C / UL 1059)	40.5 A	Rated current (Use group D / UL 1059)	10 A				
Clearance distance, min.	6.9 mm	Creepage distance, min.	9.6 mm				
Reference to approval values	Specifications are maximum values, details - see approval certificate.						
Packing							
Packaging	Box	VPE length	350 mm				
VPE width	135 mm	VPE height	40 mm				
Classifications	100 11111	VI E Holght	40 IIIII				
Classifications							
ETIM 6.0	EC002638	ETIM 7.0	EC002638				
eClass 9.0	27-44-03-09	eClass 9.1	27-44-03-09				
eClass 10.0	27-44-03-09						
Notes							
Notes	Additional colours on request						
	Rated current related to rated cross-section & min. No. of poles.						
	• P on drawing = pitch						
	 Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. 						
	 Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months 						
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.						
Approvals							
Approvals							
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White paper power electronics

connected correctly
White paper UL 600 V

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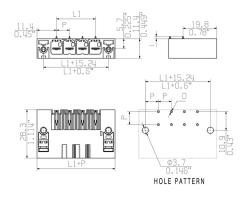
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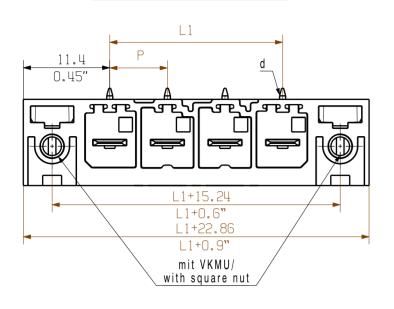
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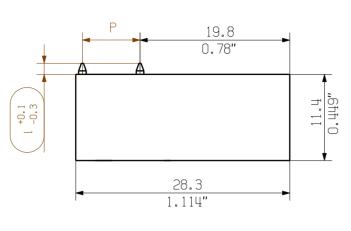
Drawings

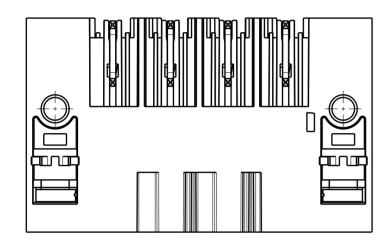
Dimensional drawing

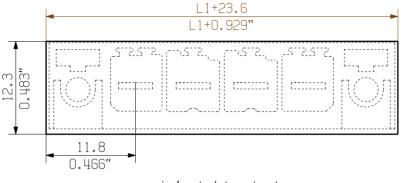


SV-SMT 7.62HP/04/270SF

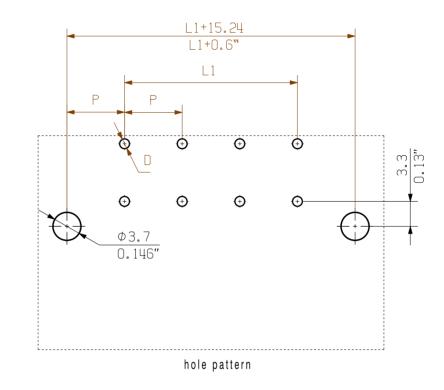




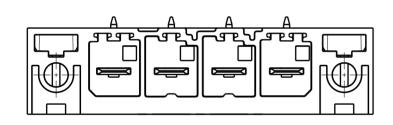


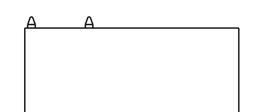


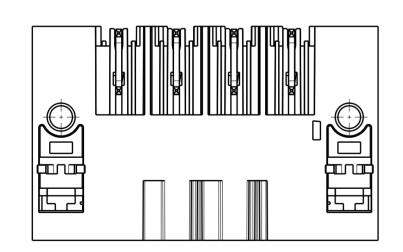
min.front plate cut out



SV-SMT 7.62HP/04/270F

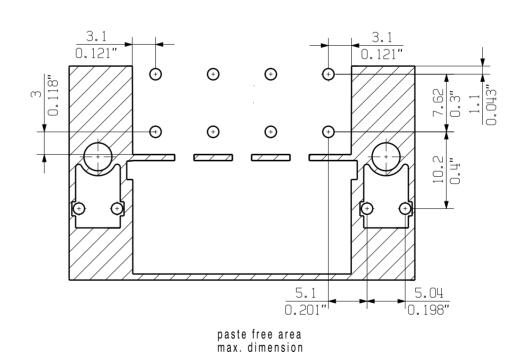






mit VKMU/

with square nut



P = Raster / pitch 7.62

 $D = \emptyset 1.4 + 0.1/-0.05$

d = 0.8x1.0

GENERAL TOLERANCE: DIN ISO 2768-m

1:1 V-SMT 7.62HP/04/270SF	1:1
ashashashash	SV-SMT 7.62HP/04/270F

For the mounting of PCBs, it should be noted that the rated data relates only to the PCB components The neccessary creepage and clearance paths must be observed in connection with the respective applicant in accordance to IEC 664 / VDE 0110. The current-carrying capacity and pitch tolerance is to be determined according to DIN IEC 326 part 3 very fine.

Weidmüller PCB components are tested to the DIN EN 61984 standard, and are valid for its field of application.

						[[mm	וו		pores	1 [111 111	j [iiici
ROMS	EC00002212			Prim PLM	Part No.: 225880		Prim	ERP P	art No	.: 24995	50000
	. First Issue Date	Max. nos		Weidmüller		r	%	63450 Drawing no.		4 Issue	
	14.11.2016	Modif	cation				/ 65	Sheet	•	of 1	7 sheet
			Date	N a m e							
			30.08.2019	Helis, Maria	SV-SI	MT 7 6	2 H C)/IT/	/an/2	70	
		Responsible		Döhrer, Karl	01-01			_FISTE	J U L	/ V · · ·	
Scale: 2	:1 Size:	A 2 Approved	09.10.2019	Lang, Thomas				IEADER			

1.5

2.6

3.5

83.82 3.3 76.20 3.0

68.58 2.7

60.96 2.4 53.34 2.1 45.72 1.8 38.10 1.5

30.48 1.2

22.86 0.9

15.24 0.6

7.62 0.3

(4)

no of L1 L1 poles [mm] [inch]

Sheet 15 of 17 sheets

11

Product file: 7407 BLF 7.50HP

Provided that the components are used to the intended purpose, all requirements with respect to the occuring of electrical, mechanical, thermic and corrosive stress will be satisfied. Drawings Assembly



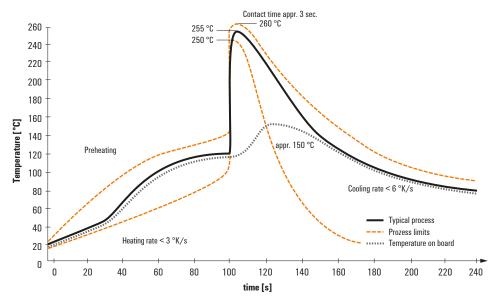
Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

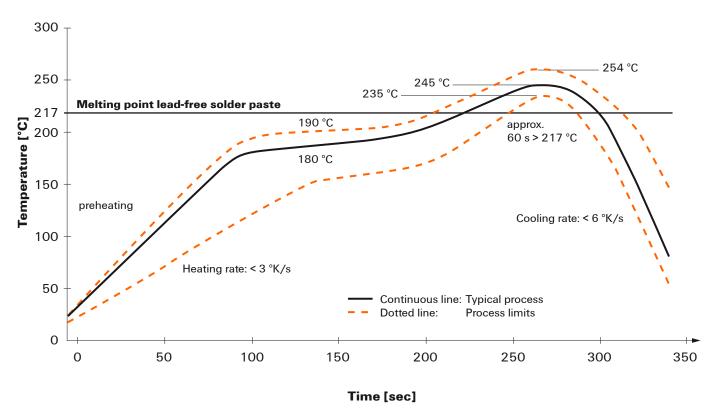


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- · Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.